

IN THE CLAIMS:

Please amend the claims as follows:

1. (currently amended) A method of creating a conductive path between two or more conductive layers, wherein the conductive layers are separated by one or more dielectric layers, the method comprising:
forming the dielectric layer with a stepped back edge;
forming a first one of the conductive layers with a stepped back edge that overhangs the stepped back edge of the dielectric layer, wherein the forming of stepped back edges of the dielectric layer and the first conductive layer exposes a surface of a second conductive layer;
~~forming a cross-shaped via in at least one of the conductive layers and in the dielectric layers;~~
applying a conductive material to the first conductive layer and the exposed portion ~~portions of the second conductive layer at least two conductive layers through the cross-shaped via,~~ the conductive material creating an electrical coupling between the first and second conductive layers; and grounding at least one of the conductive layers to a controlled ground potential.
2. (Cancelled)
3. (Previously presented) The method as recited in claim 1, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.
4. (Previously presented) The method as recited in claim 1, wherein the conductive material is a conductive adhesive.

5. (Previously presented) The method as recited in claim 1, wherein one or more of the conductive layers is grounded to the controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.
6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
9. (Previously presented) The method as recited in claim 1, wherein the conductive material is plated solder.
- 1 10. (Previously presented) The method as recited in claim 1, wherein the
2 conductive material is screen solder.
- 1 11. (Previously presented) The method as recited in claim 1, wherein the
2 conductive material is solder, and further comprising reflowing the solder.
12. (Cancelled)
13. (Cancelled)
14. (cancelled)
15. (Previously presented) The method as recited in claim 1, wherein the conductive layers form part of a lead suspension for suspending an electronic component.

16. (Previously presented) The method as recited in claim 15, wherein the electronic component is a magnetic head.
17. (Withdrawn) A method as recited in claim 14, wherein the finger is welded in place.
18. (Withdrawn) A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and a load beam.
19. (Withdrawn) A method as recited in claim 18, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel
20. (Withdrawn) A method as recited in claim 18, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.
21. (Withdrawn) A method as recited in claim 18, wherein the finger is welded in place.
22. (Withdrawn) A method as recited in claim 1, further comprising an extraneous conductive layer, the conductive material being a dimple extending from the extraneous conductive layer and contacting the exposed portions of the conductive layers.
23. (Withdrawn) A method as recited in claim 22, wherein the dimple extends through a via in at least one of the conductive layers.

24. (Withdrawn) A method as recited in claim 22, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layer is stainless steel.
25. (Withdrawn) A method as recited in claim 22, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.
26. (Withdrawn) A method as recited in claim 1, wherein the portions of the conductive layers are exposed by punching a hole through the conductive layers, the conductive material extending through the hole.
27. (Withdrawn) A method as recited in claim 26, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.
28. (Withdrawn) A method as recited in claim 26, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.
29. (New) A method as in claim 1 wherein the conductive material extends under the overhanging edge of the first conductive layer.